

7. A power module according to claim 6, wherein said external lead connected to said at least one conductive pad is connectable to a power bus to supply power to said semiconductor devices disposed thereon, said leads connected to said isolated conductive pads serve as output leads and said lead connected to said
5 conductive bar serves as a connection to the ground.

8. A power module according to claim 7, wherein at least one semiconductor device disposed on said at least one conductive pad is electrically connected to a respective one of said isolated pads by at least one wire bond, and each of said semiconductor devices is connected to said isolated conductive bar by at least one wire bond.

9. A power module according to claim 6, further comprising a plurality of pins each electrically connected to a control electrode of a respective power semiconductor device and extending from an interior of said housing element to an exterior thereof for electrical connection.

10. A power module according to claim 11, wherein a number of said pins are disposed on a first circuit board adjacent said isolated conductive pads and the remaining pins are disposed on a second circuit board adjacent said at least one conductive pad.

11. A power module according to claim 1, further comprising at least one circuit board disposed inside said housing element and including at least one pin electrically connected to a conductive land, said conductive land being electrically connected to the control electrode of said at least one semiconductor device.